



## Material Content Data Sheet



Sales Product Name	ICE2PCS02G			Issued		28. October 2019		
MA#	MA005399596							
Package	PG-DSO-8-78			Weight*		82.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.787	2.17	2.17	21658	21658
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		102	
	non noble metal	zinc	7440-66-6	0.034	0.04		408	
	non noble metal	iron	7439-89-6	0.673	0.82		8162	
	non noble metal	copper	7440-50-8	27.342	33.14	34.01	331397	340069
wire	noble metal	gold	7440-57-5	0.114	0.14	0.14	1382	1382
encapsulation	organic material	carbon black	1333-86-4	0.151	0.18		1834	
	plastics	epoxy resin	-	4.893	5.93		59307	
	inorganic material	silicondioxide	60676-86-0	45.399	55.02	61.13	550270	611411
leadfinish	non noble metal	tin	7440-31-5	0.876	1.06	1.06	10616	10616
plating	noble metal	silver	7440-22-4	0.131	0.16	0.16	1592	1592
glue	plastics	acrylic resin	-	0.241	0.29		2920	
	noble metal	silver	7440-22-4	0.854	1.04	1.33	10352	13272
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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